ABSTRACT

Provided are a method and a jig for holding a silicon wafer, which are applied to the production of the silicon wafer having {110} or {100} plane as its principal surface, in which the silicon wafer is held while a silicon wafer holding positions are properly defined at wafer edge regions relative to the reference direction as being from the center of the silicon wafer toward <110> in crystal orientation in parallel to the wafer surface. In handling the silicon wafer, generation of contact scratches is suppressed as little as possible, and a fracture which is caused by development of the crack initiating from easily generated contact scratches can be prevented in the silicon wafer, particularly in the silicon wafer having {110} plane as its principal surface.